

PRODUCT DATA SHEET

WS-829

Halogen-Free Ball-Attach and LED Die-Attach Flux

Introduction

Ball-Attach Flux WS-829 is a halogen-free water-soluble ball-attach and LED die-attach flux designed for use in pin transfer and printing applications for ball-attachment to substrates (BGA manufacturing) and wafer/panel (WLP/PLP manufacturing). **WS-829** can also be used for LED die-attach application. Its thixotropic property allows it to be printed on a substrate consistently with superb print definition for very small deposit without slumping. Its rheology is specifically designed for use with even the smallest gravity-fed spheres. **WS-829** has an activator system powerful enough to promote wetting on the most demanding substrate metallizations. Flux residue of **WS-829** can be effectively cleaned with DI water only without leaving any contamination behind.

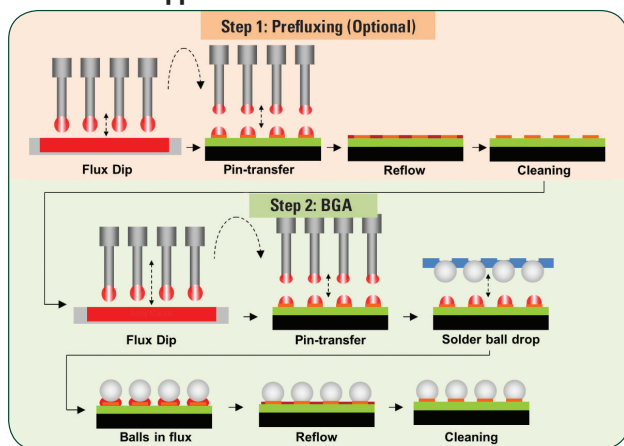


Features

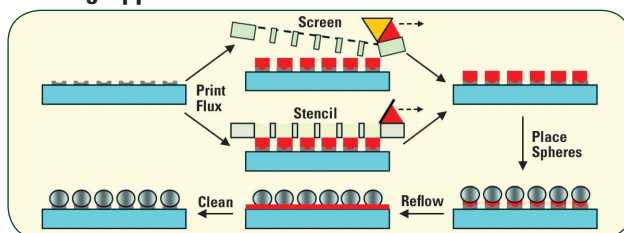
- Designed for ball-attach process, pin transfer, and printing applications
- Also suitable for miniLED or microLED die-attach application, printing through stencil for ultrafine aperture
- Halogen-free—per IPC and IEC specifications
- Flux rheology suitable even for smallest sphere size
- Thixotropic property ensures good print definition with minimal slump
- Promotes excellent solderability and wetting on a wide range of surfaces
 - Good results on AuNi and even on oxidized Cu-OSP (up to 0.3mm thick OSP)
- Promotes strong, low-voiding joints
- Cleans well with room temperature DI water
 - Saves money on water heating
 - No undesirable flux residue or contamination
- Designed for Pb-free applications
 - Suitable for all high-tin solders
- Ensures consistent joint quality by providing consistent pin transfer and printing performance over extended periods
- Reduces “double ball” and “missing balls”
 - Maintains tackiness during heating, results in minimal sphere movement
- Reflows in air or nitrogen
- Stable at room temperature for up to 6 months

Standard Ball-Attach Process

Pin Transfer Application



Printing Application



Flux Properties

Industry Standard Test Results and Classification	
Flux Classification	ORH0
Based on the testing required by IPC J-STD-004A.	
Halogen-free per IEC 61249-2-21, Test Method EN14582	<900 ppm Cl <900 ppm Br <1,500ppm Total

	Value	Test Method
Typical Viscosity	18kcps (5 minutes)	Brookfield HB DVII±CP (5rpm)
Typical Acid Number	84mg KOH/g	Titration
Typical Tack Strength	300g	J-STD-005 (IPC-TM-650: 2.4.44)
Shelf Life	0–30°C for 6 months	Viscosity change/ microscope examination

All information is for reference only.
Not to be used as incoming product specifications.

From One Engineer To Another®



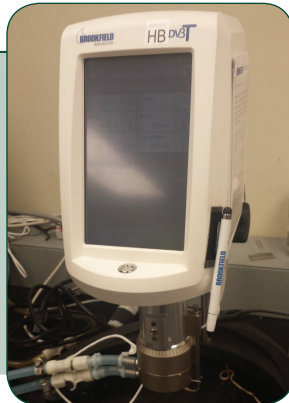
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Pin Transfer

Viscosity Test Method

- **Equipment**
 - Brookfield Cone & Plate
 - Model: DV3THBCB
- **Parameters**
 - Spindle: CP-51
 - Temperature: 25°C
 - Rpm: 10rpm



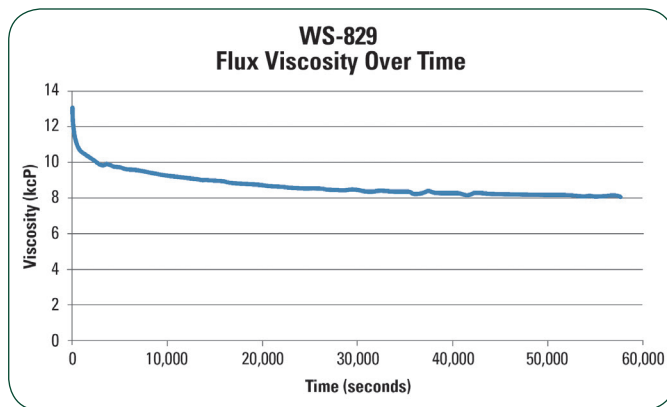
Tack Test Method

- **Equipment**
 - Texture Technologies TA.XT2
- **Parameters**
 - Ambient Conditions
 - Humidity: 50% ± 3%
 - Room Temperature: 21.5°C ± 2°C

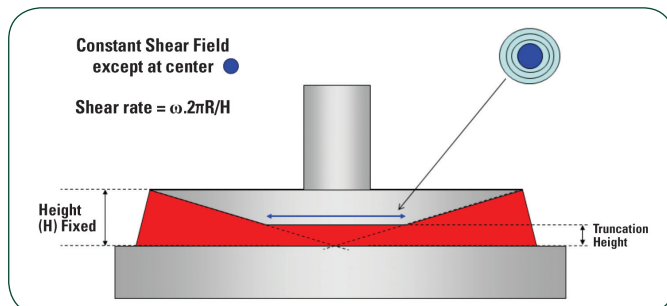
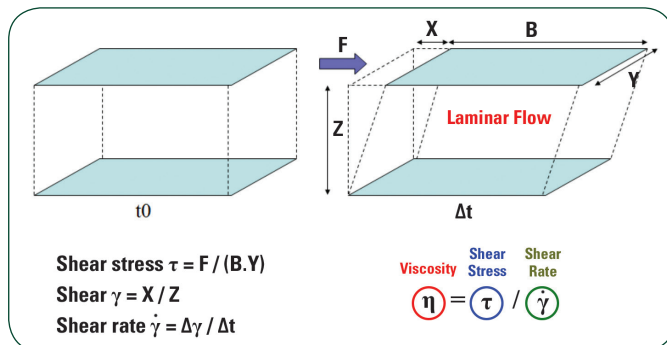
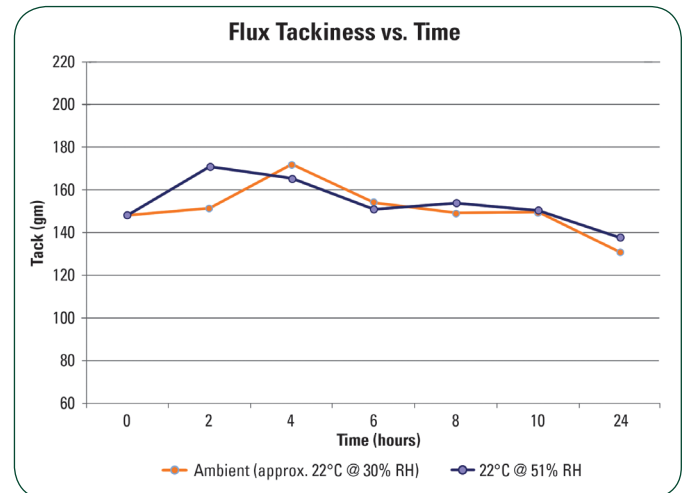


Viscosity as a Function of Time

Viscosity Controls



Tack as a Function of Time



Consistent Flux Deposition

WS-829's consistent viscosity and tack ensures consistent flux deposit sizes and eliminates missing ball before reflow.

WS-829 Halogen-Free Ball-Attach and LED Die-Attach Flux

Printing



Printing Response-to-Pause (RTP) Test Method

1. Knead 30 cycles @ 50mm/sec
 - a. Print one test board (0 hours)
 - b. Run a wet/dry/vac understencil wipe and pause for 1 hour
2. Knead 80 cycles @ 50mm/sec
 - a. Print one test board (1 hour)
 - b. Run a wet/dry/vac understencil wipe and pause for 1 hour
3. Repeat Step 2 another 3 times for printing test board at 2, 3, and 4 hours

Consistent Printing Performance

Consistent printing performance over extended periods ensures good joint quality.

Slump Test

- Inspect test boards from above test every 30 minutes for up to 2 hours

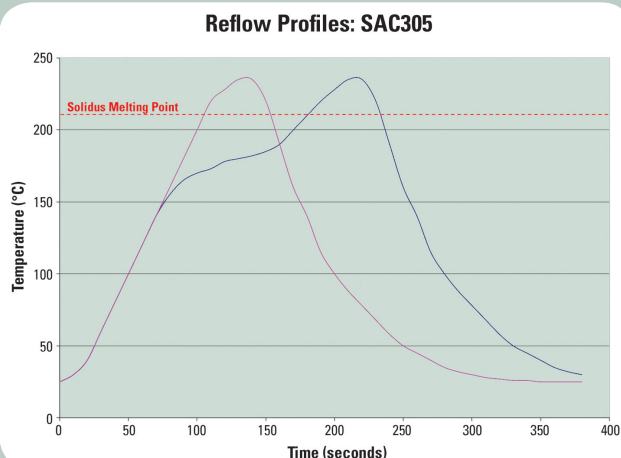
Results			
(Pictures at different time intervals are selected since all show minimal variation)			
	Initial Flux Printed	60-Minute Flux Printed	120-Minute Flux Printed
0 Hours			
2 Hours			
4 Hours			

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Reflow

Reflow

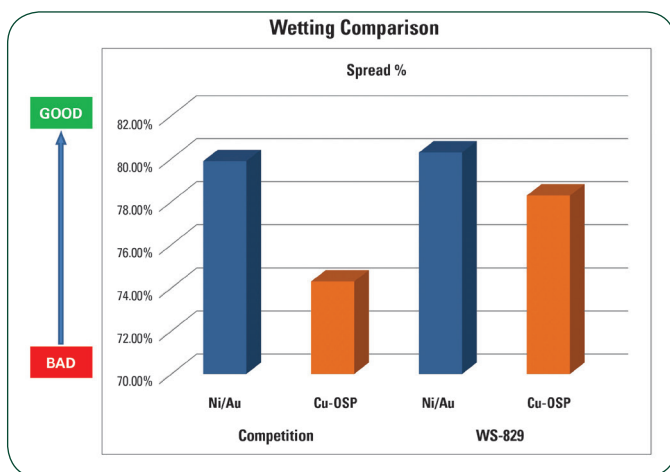
Recommended Profile:



WS-829 is suitable for air and nitrogen reflow, and can work well in a variety of reflow profiles.

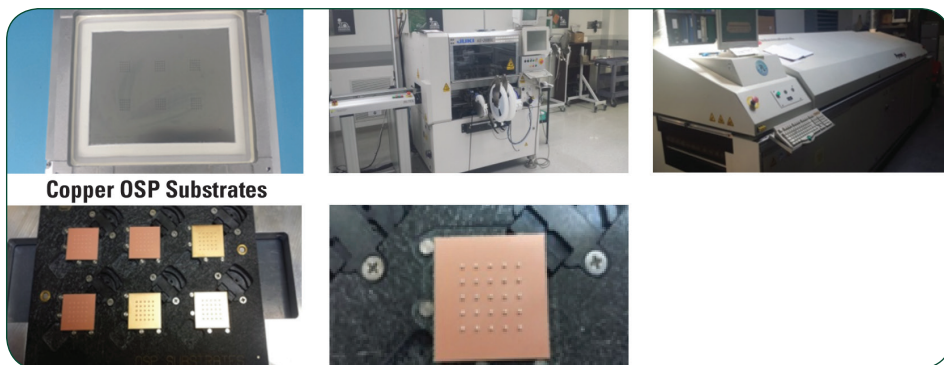
$$S_R = \frac{D-H}{D} \times 100 \dots\dots\dots (16)$$

where, S_R : spreading ratio (%)
 H : height of the spread solder (mm)
 D : diameter of the solder, when it is assumed to be a sphere (mm)
 $D = 1.24V^{1/3}$
 V : mass (12)/density of tested solder



Eliminates Missing Ball and Increases Joint Strength

WS-829 eliminates missing ball during reflow by high viscosity and rapid soldering. Joint strength is high due to good wetting.



Solderability Test Method

- Print flux onto metallized surface
- Place spheres onto flux deposit
- Reflow (air or N_2 [typical])
- Measure reflowed height deposit
- Calculate spreading ratio (wetting)

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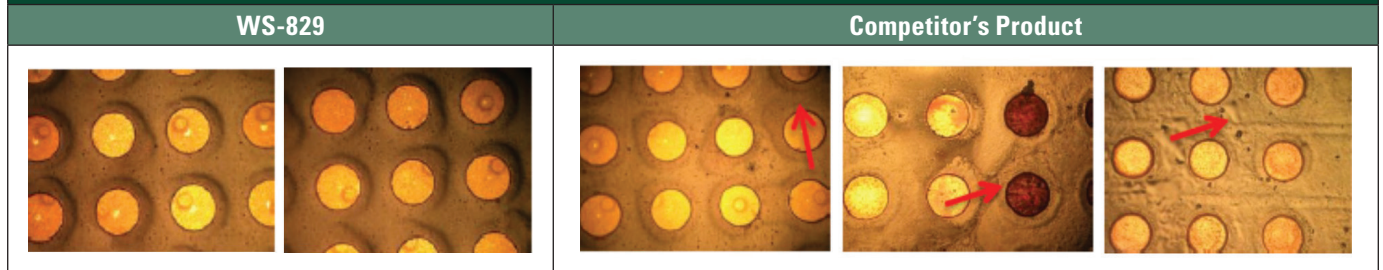
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Cleaning

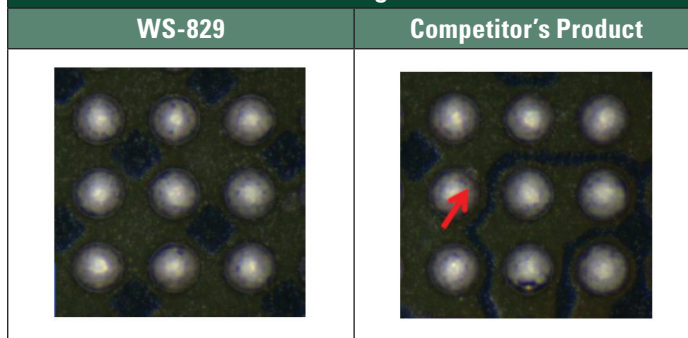
Cleaning Process

Using in-line DI water spray cleaning equipment

After Cu-OSP Pre-Cleaning Process



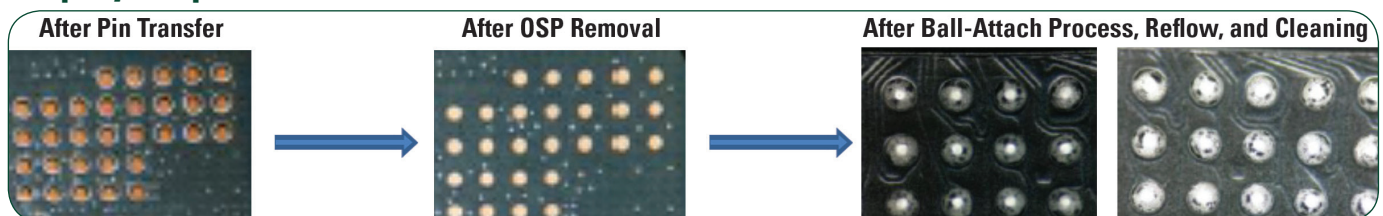
After Ball-Attach and Cleaning Process



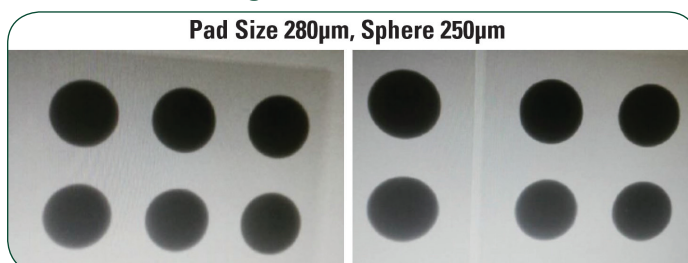
Best-in-Class Cleanability

WS-829 was able to remove Cu-OSP and most stubborn contamination on the substrate, and residue was easily removable with standard cleaning process.

Step-by-Step Process



Minimal Voiding



Contact our engineers: askus@indium.com

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Heterogeneous Integration & Assembly Materials

3D Logic / Memory and Flip-Chip

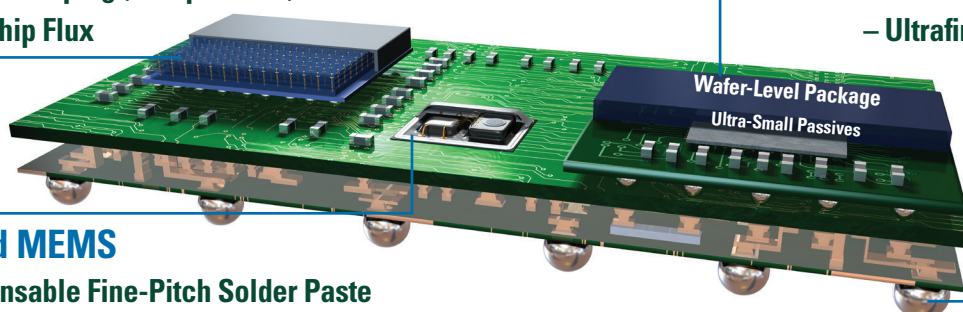
- Wafer Bumping (Bump Fusion) Flux
- Flip-Chip Flux

System-in-Package

- Wafer-Level Ball-Attach Flux
- Ultrafine-Pitch Solder Paste

Lidded MEMS

- Dispensable Fine-Pitch Solder Paste



Recommended Semiconductor Fluxes and Solder Pastes

Material Group	Material Type	Material Name	Flux Type	Halogen-Free	Application	Comments
FLUX	Wafer Bumping Flux	WS-3543	Water wash	Yes	Spin coating	High viscosity for taller copper pillars and larger bumps (>40 microns)
		WS-3401	Water wash	Yes	Spin coating	Low viscosity for smaller pillars and bumps
	Flip-Chip Flux	WS-446	Water wash	No	Dipping	Best flux for poor solderability
		WS-688	Water wash	Yes	Dipping (can be sprayed at 60°C)	Minimizes voiding
		NC-26-A	Ultra-low residue no-clean	Yes	Dipping	Best compatibility with CUF/MUF
		NC-26S	Ultra-low residue no-clean	Yes	Dipping	Avoids capillary flow up to die surface for fine-pitch devices
	Flip-Chip & Ball-Attach Flux	WS-446HF	Water wash	Yes	Dipping	Best all-around halogen-free flip-chip and ball-mount flux, easily cleaned
	Ball-Attach Flux	WS-446-AL	Water wash	No	Pin transfer	Best flux for poor solderability
		WS-575-C	Water wash	Compliant	Pin transfer	Eliminates the prefluxing step for OSP
		WS-823	Water wash	Yes	Pin transfer	Best all-around halogen-free ball-attach flux, easily cleaned
		WS-829	Water wash	Yes	Pin transfer/ Printing	Best in cleanability, suitable for wafer-level and panel-level packaging (WLP and PLP), and LED die-attach
		WS-759	Water wash	Yes	Printing	Stable printing flux for wafer-level and panel-level packaging (WLP and PLP)

Material Group	Material Type	Material Name	Flux Type	Halogen-Free	Alloy	Comments
SOLDER PASTE	Die-Attach Solder Paste	SMQ75	No-Clean ("Power-Safe")	Yes	All high-Pb and Sb-containing alloys	Ultra-low residue "Power-Safe" (no-clean) paste suitable for clip-bonded devices
		SMQ51-SC	Solvent clean	No		Best all-around cleanable die-attach paste
		BiAgX®	Solvent clean	Yes	BiAgX® mixed alloy system	High-temperature Pb-free solder paste
	SiP Solder Paste	Indium3.2HF	Water wash	Yes	SAC305 and other Pb-free alloys	Type 6-SG solder paste suitable for ultrafine-pitch printing Designed for 01005 and smaller discrete devices

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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